

Materials List for:

A Performance-testing Platform for a Conduction Micropump with an FR-4 Copper-clad Electrode Plate

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Materials

Name	Company	Catalog Number	Comments
Amperemeter	-	85C1-MA	
DC high voltage power supply	NanTong Jianuo electric device company	GY-WY500-1	
Fuse	-	-	
Ultrasonic cleaner	Derui ultrasonic device company	-	
Soldering iron	-	-	